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(54) Title: COOLING SYSTEM FOR A DATA CENTER THAT INCLUDES AN OFFSET COOLING TECHNOLOGY

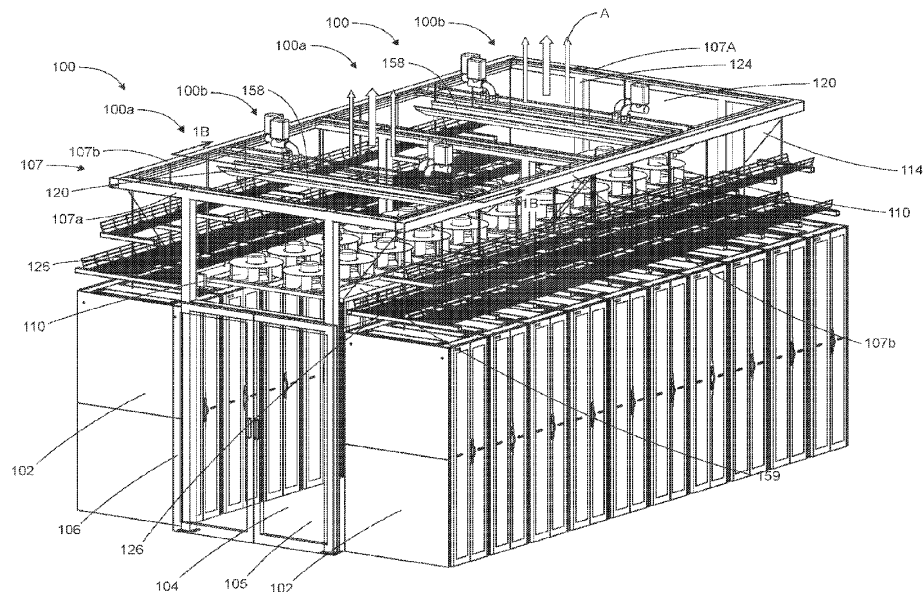


FIG. 1A

(57) Abstract: A data center cooling system, including a support structure having a lower portion and an upper portion, one or more fans supported by the support structure at a height that is equal to or greater than a height of the electronics cabinets, and a heat exchanger having one or more cooling coils supported at the upper portion of the support structure. In some embodiments, the cooling coils can be supported by the upper portion of the support structure so as to be above the top of and/or over one or more of the electronics cabinets. The fans can be configured to draw air from the one or two rows of electronics cabinets and to cause the air to be passed through the heat exchanger to cool the warmer air from the electronics cabinets.

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WO 2022/115852 A1

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